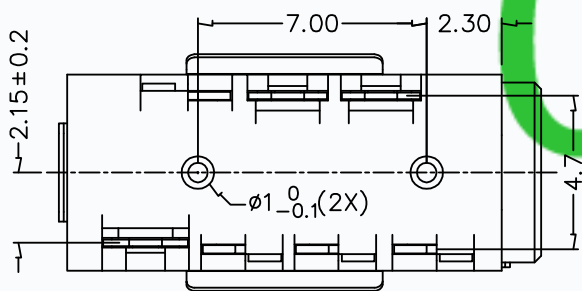
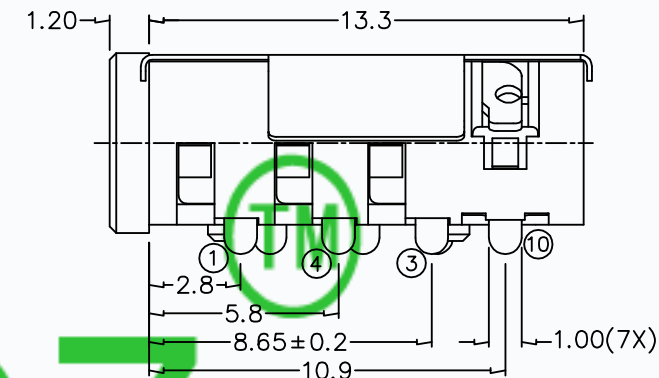
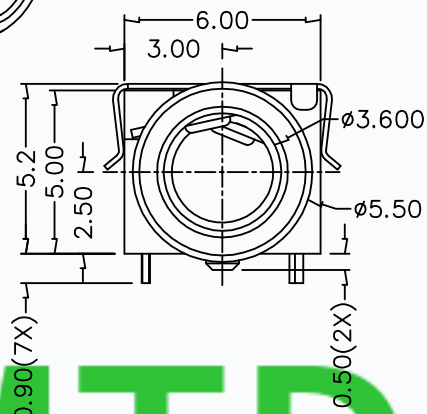
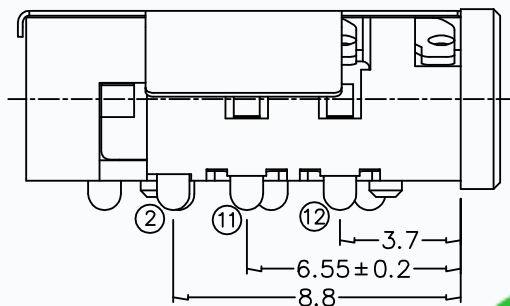
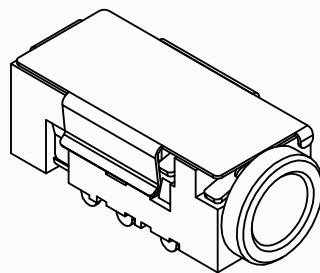


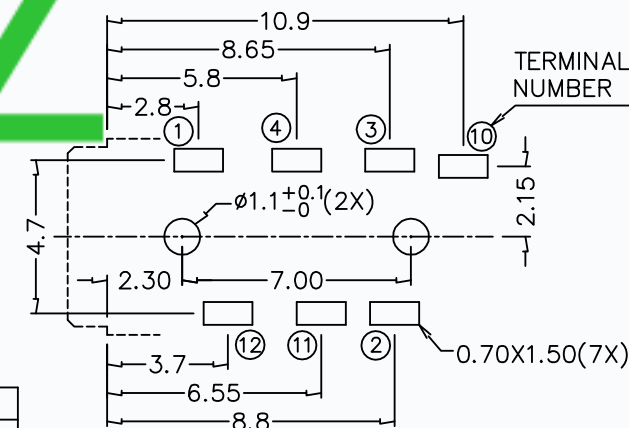
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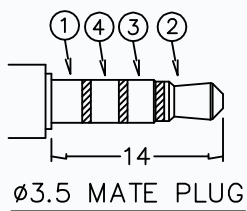
CMTDDZ

\* MATERIAL

- TERMINAL 1 : COPPER ALLOY
- TERMINAL 2 : COPPER ALLOY
- TERMINAL 3 : COPPER ALLOY
- TERMINAL 4 : COPPER ALLOY
- TERMINAL 10 : BRASS
- TERMINAL 11 : BRASS
- TERMINAL 12 : BRASS
- SHIELD : STAINLESS STEEL
- HOUSING : PA6T



PCB LAYOUT (BOTTOM VIEW)



MODEL NO.	T13-35917S1-2	T13-35916AS1-2	T13-35915AS1-2	T13-35914S1-2	T13-35915S1-2
SCHEMATIC					

APPD.	DESCRIPTIONS OF REVISION	<p><b>TOLERANCE</b> UNLESS SPECIFIED</p> <p>WITHIN 1.5mm : ±0.1mm OVER 1.5mm : ±0.2mm</p>	<p>THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF DONGGUAN TIANDU ELECTRONICS CO.,LTD. AND SHALL NOT BE REPRODUCED. COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF DONGGUAN TIANDU ELECTRONICS CO., LTD.</p>	TITLE : 3.5mm SMD PHONE JACK	UNIT : mm	DRWG NO.: CMTDDZ-T13-3591S1-00		
				MODEL: T13-3591S1-2	SCALE: 3:1	DWN.	ERIC	2013-6-17
				<p><b>CMTDDZ</b> 东莞市田都电子有限公司 DONGGUAN TIANDU ELECTRONICS CO.,LTD.</p>			CHK'D	MAIKO
				APPD.	Coco	2013-6-17		